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74HC132; 74HCT132

Quad 2-input NAND Schmitt trigger

Rev. 4 — 1 December 2015

Product data sheet

1. General description

The 74HC132; 74HCT132 is a quad 2-input NAND gate with Schmitt-trigger inputs. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} . Schmitt trigger inputs transform slowly changing input signals into sharply defined jitter-free output signals.

2. Features and benefits

- Complies with JEDEC standard no. 7A
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Applications

- Wave and pulse shapers
- Astable multivibrators
- Monostable multivibrators



4. Ordering information

Table 1. Ordering information

| Type number | Package | | | Version |
|-------------|-------------------|---------|--|----------|
| | Temperature range | Name | Description | |
| 74HC132D | -40 °C to +125 °C | SO14 | plastic small outline package; 14 leads; body width 3.9 mm | SOT108-1 |
| 74HCT132D | | | | |
| 74HC132DB | -40 °C to +125 °C | SSOP14 | plastic shrink small outline package; 14 leads; body width 5.3 mm | SOT337-1 |
| 74HCT132DB | | | | |
| 74HC132PW | -40 °C to +125 °C | TSSOP14 | plastic thin shrink small outline package; 14 leads; body width 4.4 mm | SOT402-1 |
| 74HCT132PW | | | | |

5. Functional diagram

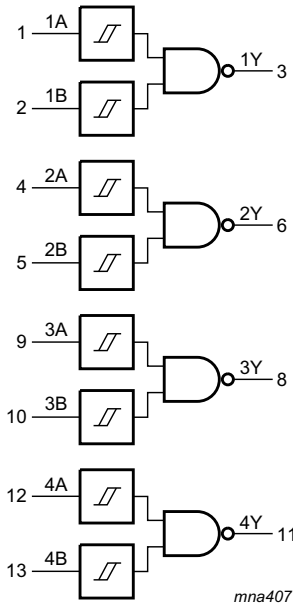


Fig 1. Logic symbol

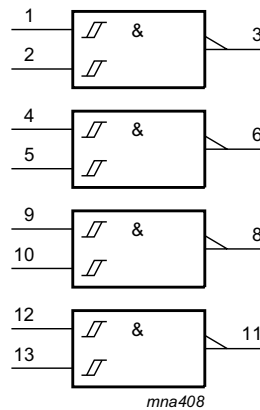


Fig 2. IEC logic symbol

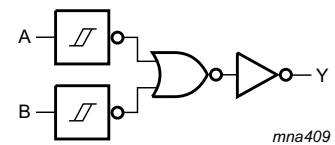


Fig 3. Logic diagram (one Schmitt trigger)

6. Pinning information

6.1 Pinning

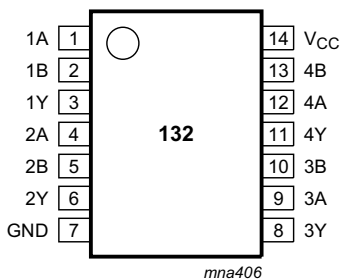


Fig 4. Pin configuration SO14 and (T)SSOP14

6.2 Pin description

Table 2. Pin description

| Symbol | Pin | Description |
|-----------------|--------------|----------------|
| 1A to 4A | 1, 4, 9, 12 | data input |
| 1B to 4B | 2, 5, 10, 13 | data input |
| 1Y to 4Y | 3, 6, 8, 11 | data output |
| GND | 7 | ground (0 V) |
| V _{CC} | 14 | supply voltage |

7. Functional description

Table 3. Function table^[1]

| Input | | Output |
|-------|----|--------|
| nA | nB | nY |
| L | L | H |
| L | H | H |
| H | L | H |
| H | H | L |

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care.

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|-------------------------|--|------|----------|------|
| V_{CC} | supply voltage | | -0.5 | +7 | V |
| I_{IK} | input clamping current | $V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$ [1] | - | ± 20 | mA |
| I_{OK} | output clamping current | $V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$ [1] | - | ± 20 | mA |
| I_O | output current | $-0.5\text{ V} < V_O < V_{CC} + 0.5\text{ V}$ | - | ± 25 | mA |
| I_{CC} | supply current | | - | 50 | mA |
| I_{GND} | ground current | | -50 | - | mA |
| T_{stg} | storage temperature | | -65 | +150 | °C |
| P_{tot} | total power dissipation | SO14, and (T)SSOP14 packages [2] | - | 500 | mW |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO14 package: P_{tot} derates linearly with 8 mW/K above 70 °C.
For (T)SSOP14 packages: P_{tot} derates linearly with 5.5 mW/K above 60 °C.

9. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

| Symbol | Parameter | Conditions | 74HC132 | | | 74HCT132 | | | Unit |
|-----------|---------------------|------------|---------|-----|----------|----------|-----|----------|------|
| | | | Min | Typ | Max | Min | Typ | Max | |
| V_{CC} | supply voltage | | 2.0 | 5.0 | 6.0 | 4.5 | 5.0 | 5.5 | V |
| V_I | input voltage | | 0 | - | V_{CC} | 0 | - | V_{CC} | V |
| V_O | output voltage | | 0 | - | V_{CC} | 0 | - | V_{CC} | V |
| T_{amb} | ambient temperature | | -40 | +25 | +125 | -40 | +25 | +125 | °C |

10. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|------------------|---------------------------|--|-------|------|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74HC132 | | | | | | | | | | |
| V _{OH} | HIGH-level output voltage | V _I = V _{T+} or V _{T-} | | | | | | | | |
| | | I _O = -20 μA; V _{CC} = 2.0 V | 1.9 | 2.0 | - | 1.9 | - | 1.9 | - | V |
| | | I _O = -20 μA; V _{CC} = 4.5 V | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -20 μA; V _{CC} = 6.0 V | 5.9 | 6.0 | - | 5.9 | - | 5.9 | - | V |
| | | I _O = -4.0 mA; V _{CC} = 4.5 V | 3.98 | 4.32 | - | 3.84 | - | 3.7 | - | V |
| | | I _O = -5.2 mA; V _{CC} = 6.0 V | 5.48 | 5.81 | - | 5.34 | - | 5.2 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{T+} or V _{T-} | | | | | | | | |
| | | I _O = 20 μA; V _{CC} = 2.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 4.5 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 6.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 4.0 mA; V _{CC} = 4.5 V | - | 0.15 | 0.26 | - | 0.33 | - | 0.4 | V |
| | | I _O = 5.2 mA; V _{CC} = 6.0 V | - | 0.16 | 0.26 | - | 0.33 | - | 0.4 | V |
| I _I | input leakage current | V _I = V _{CC} or GND; V _{CC} = 6.0 V | - | - | ±0.1 | - | ±1.0 | - | ±1.0 | μA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V | - | - | 2.0 | - | 20 | - | 40 | μA |
| C _I | input capacitance | | - | 3.5 | - | - | - | - | - | pF |
| 74HCT132 | | | | | | | | | | |
| V _{OH} | HIGH-level output voltage | V _I = V _{T+} or V _{T-} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = -20 μA | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -4.0 mA | 3.98 | 4.32 | - | 3.84 | - | 3.7 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{T+} or V _{T-} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = 20 μA; I _O = 4.0 mA; | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | | - | 0.15 | 0.26 | - | 0.33 | - | 0.4 | V |
| I _I | input leakage current | V _I = V _{CC} or GND; V _{CC} = 5.5 V | - | - | ±0.1 | - | ±1.0 | - | ±1.0 | μA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 2.0 | - | 20 | - | 40 | μA |
| ΔI _{CC} | additional supply current | per input pin; V _I = V _{CC} - 2.1 V; I _O = 0 A; other inputs at V _{CC} or GND; V _{CC} = 4.5 V to 5.5 V | - | 30 | 108 | - | 135 | - | 147 | μA |
| C _I | input capacitance | | - | 3.5 | - | - | - | - | - | pF |

11. Dynamic characteristics

Table 7. Dynamic characteristics

$GND = 0\text{ V}$; $C_L = 50\text{ pF}$; for load circuit see [Figure 6](#).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +125 °C | | Unit |
|-----------------|-------------------------------|--|-------|-----|-----|-------------------|--------------|------|
| | | | Min | Typ | Max | Max (85 °C) | Max (125 °C) | |
| 74HC132 | | | | | | | | |
| t_{pd} | propagation delay | nA, nB to nY; see Figure 5 [1] | | | | | | |
| | | $V_{CC} = 2.0\text{ V}$ | - | 36 | 125 | 155 | 190 | ns |
| | | $V_{CC} = 4.5\text{ V}$ | - | 13 | 25 | 31 | 38 | ns |
| | | $V_{CC} = 5.0\text{ V}$; $C_L = 15\text{ pF}$ | - | 11 | - | - | - | ns |
| | | $V_{CC} = 6.0\text{ V}$ | - | 10 | 21 | 26 | 32 | ns |
| t_t | transition time | see Figure 5 [2] | | | | | | |
| | | $V_{CC} = 2.0\text{ V}$ | - | 19 | 75 | 95 | 110 | ns |
| | | $V_{CC} = 4.5\text{ V}$ | - | 7 | 15 | 19 | 22 | ns |
| | | $V_{CC} = 6.0\text{ V}$ | - | 6 | 13 | 16 | 19 | ns |
| C_{PD} | power dissipation capacitance | per package; $V_I = GND$ to V_{CC} [3] | - | 24 | - | - | - | pF |
| 74HCT132 | | | | | | | | |
| t_{pd} | propagation delay | nA, nB to nY; see Figure 5 [1] | | | | | | |
| | | $V_{CC} = 4.5\text{ V}$ | - | 20 | 33 | 41 | 50 | ns |
| | | $V_{CC} = 5.0\text{ V}$; $C_L = 15\text{ pF}$ | - | 17 | - | - | - | ns |
| t_t | transition time | $V_{CC} = 4.5\text{ V}$; see Figure 5 [2] | - | 7 | 15 | 19 | 22 | ns |
| C_{PD} | power dissipation capacitance | per package; $V_I = GND$ to $V_{CC} - 1.5\text{ V}$ [3] | - | 20 | - | - | - | pF |

[1] t_{pd} is the same as t_{PHL} and t_{PLH} .

[2] t_t is the same as t_{THL} and t_{TLH} .

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW):

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

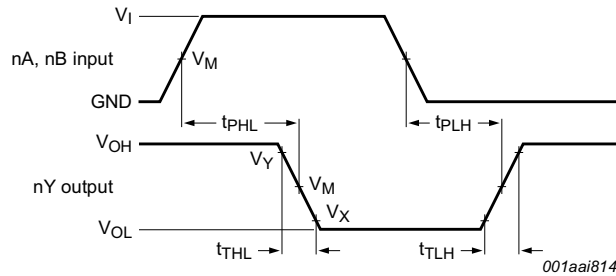
C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

$\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

12. Waveforms

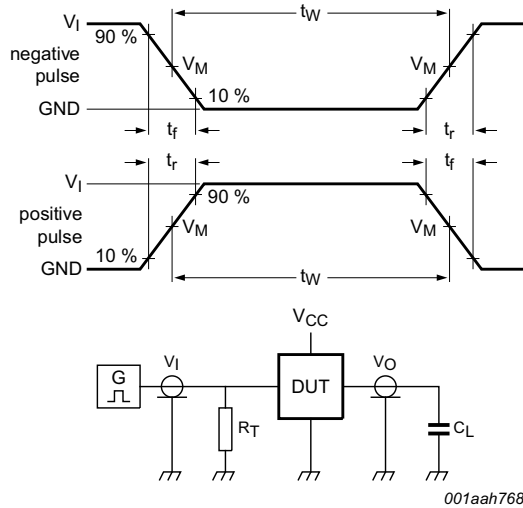


Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 5. Input to output propagation delays

Table 8. Measurement points

| Type | Input | Output | | |
|----------|-------------|-------------|-------------|-------------|
| | V_M | V_M | V_X | V_Y |
| 74HC132 | $0.5V_{CC}$ | $0.5V_{CC}$ | $0.1V_{CC}$ | $0.9V_{CC}$ |
| 74HCT132 | 1.3 V | 1.3 V | $0.1V_{CC}$ | $0.9V_{CC}$ |



Test data is given in [Table 9](#).
 Definitions test circuit:
 R_T = termination resistance should be equal to output impedance Z_o of the pulse generator.
 C_L = load capacitance including jig and probe capacitance.

Fig 6. Test circuit for measuring switching times

Table 9. Test data

| Type | Input | | Load | Test |
|----------|----------|------------|--------------|--------------------|
| | V_I | t_r, t_f | C_L | |
| 74HC132 | V_{CC} | 6.0 ns | 15 pF, 50 pF | t_{PLH}, t_{PHL} |
| 74HCT132 | 3.0 V | 6.0 ns | 15 pF, 50 pF | t_{PLH}, t_{PHL} |

13. Transfer characteristics

Table 10. Transfer characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V); see Figure 7 and Figure 8.

| Symbol | Parameter | Conditions | $T_{amb} = 25\text{ }^\circ\text{C}$ | | | $T_{amb} = -40\text{ }^\circ\text{C}$ to $+85\text{ }^\circ\text{C}$ | | $T_{amb} = -40\text{ }^\circ\text{C}$ to $+125\text{ }^\circ\text{C}$ | | Unit |
|-----------------|----------------------------------|-------------------------|--------------------------------------|------|------|---|------|--|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74HC132 | | | | | | | | | | |
| V_{T+} | positive-going threshold voltage | $V_{CC} = 2.0\text{ V}$ | 0.7 | 1.18 | 1.5 | 0.7 | 1.5 | 0.7 | 1.5 | V |
| | | $V_{CC} = 4.5\text{ V}$ | 1.7 | 2.38 | 3.15 | 1.7 | 3.15 | 1.7 | 3.15 | V |
| | | $V_{CC} = 6.0\text{ V}$ | 2.1 | 3.14 | 4.2 | 2.1 | 4.2 | 2.1 | 4.2 | V |
| V_{T-} | negative-going threshold voltage | $V_{CC} = 2.0\text{ V}$ | 0.3 | 0.63 | 1.0 | 0.3 | 1.0 | 0.3 | 1.0 | V |
| | | $V_{CC} = 4.5\text{ V}$ | 0.9 | 1.67 | 2.2 | 0.9 | 2.2 | 0.9 | 2.2 | V |
| | | $V_{CC} = 6.0\text{ V}$ | 1.2 | 2.26 | 3.0 | 1.2 | 3.0 | 1.2 | 3.0 | V |
| V_H | hysteresis voltage | $V_{CC} = 2.0\text{ V}$ | 0.2 | 0.55 | 1.0 | 0.2 | 1.0 | 0.2 | 1.0 | V |
| | | $V_{CC} = 4.5\text{ V}$ | 0.4 | 0.71 | 1.4 | 0.4 | 1.4 | 0.4 | 1.4 | V |
| | | $V_{CC} = 6.0\text{ V}$ | 0.6 | 0.88 | 1.6 | 0.6 | 1.6 | 0.6 | 1.6 | V |
| 74HCT132 | | | | | | | | | | |
| V_{T+} | positive-going threshold voltage | $V_{CC} = 4.5\text{ V}$ | 1.2 | 1.41 | 1.9 | 1.2 | 1.9 | 1.2 | 1.9 | V |
| | | $V_{CC} = 5.5\text{ V}$ | 1.4 | 1.59 | 2.1 | 1.4 | 2.1 | 1.4 | 2.1 | V |
| V_{T-} | negative-going threshold voltage | $V_{CC} = 4.5\text{ V}$ | 0.5 | 0.85 | 1.2 | 0.5 | 1.2 | 0.5 | 1.2 | V |
| | | $V_{CC} = 5.5\text{ V}$ | 0.6 | 0.99 | 1.4 | 0.6 | 1.4 | 0.6 | 1.4 | V |
| V_H | hysteresis voltage | $V_{CC} = 4.5\text{ V}$ | 0.4 | 0.56 | - | 0.4 | - | 0.4 | - | V |
| | | $V_{CC} = 5.5\text{ V}$ | 0.4 | 0.60 | - | 0.4 | - | 0.4 | - | V |

14. Transfer characteristics waveforms

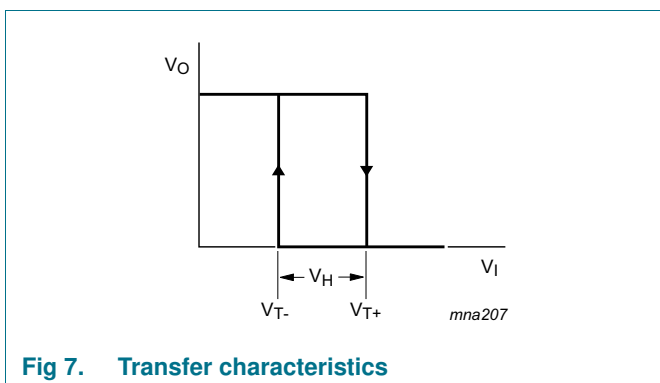


Fig 7. Transfer characteristics

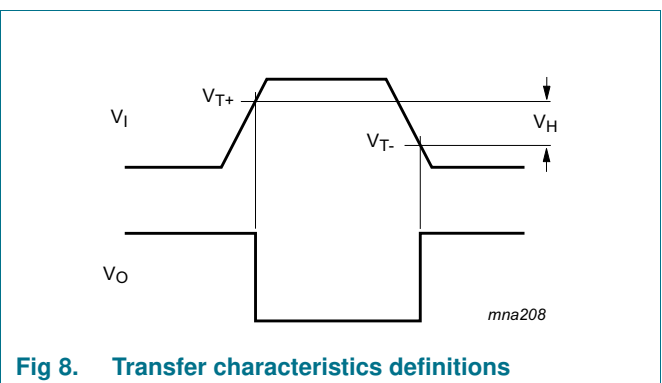
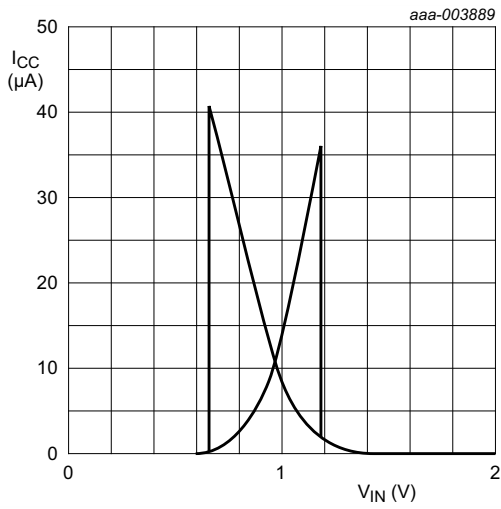
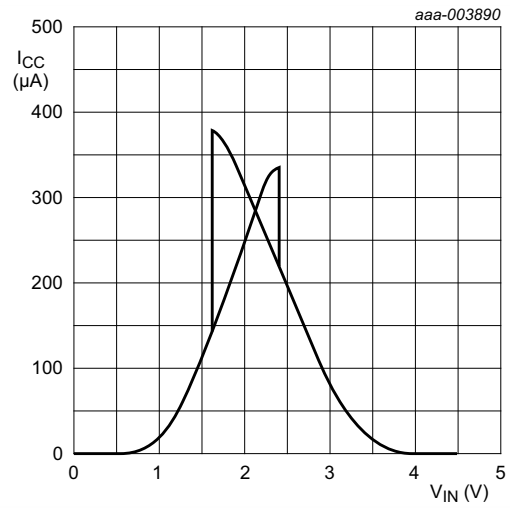


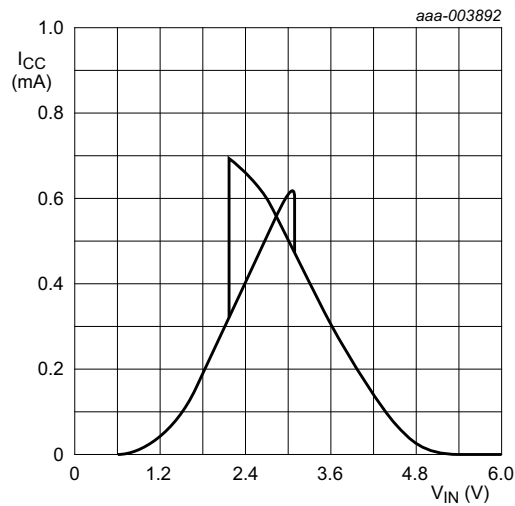
Fig 8. Transfer characteristics definitions



a. $V_{CC} = 2.0\text{ V}$

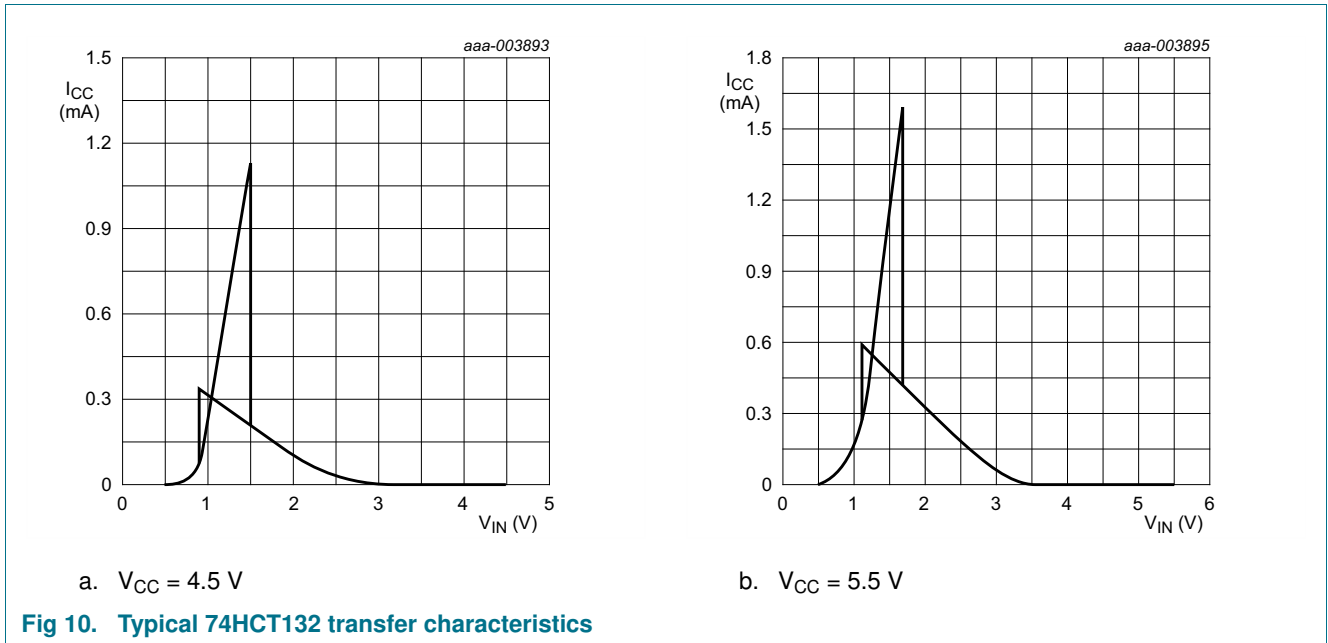


b. $V_{CC} = 4.5\text{ V}$



c. $V_{CC} = 6.0\text{ V}$

Fig 9. Typical 74HC132 transfer characteristics



15. Application information

The slow input rise and fall times cause additional power dissipation, this can be calculated using the following formula:

$$P_{add} = f_i \times (t_r \times \Delta I_{CC(AV)} + t_f \times \Delta I_{CC(AV)}) \times V_{CC} \text{ where:}$$

P_{add} = additional power dissipation (μ W);

f_i = input frequency (MHz);

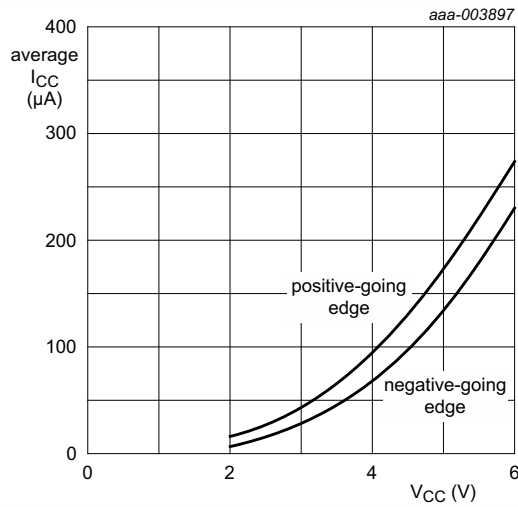
t_r = rise time (ns); 10 % to 90 %;

t_f = fall time (ns); 90 % to 10 %;

$\Delta I_{CC(AV)}$ = average additional supply current (μ A).

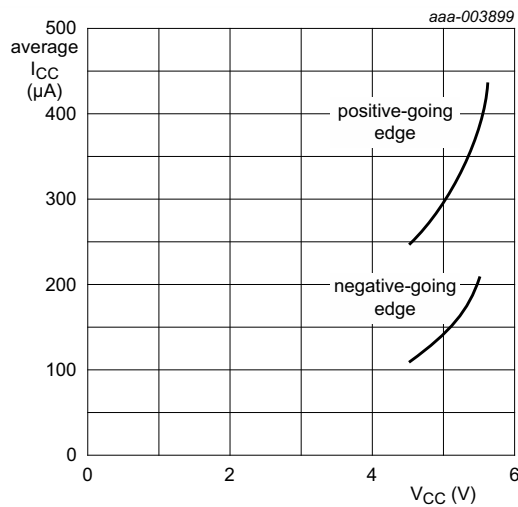
Average $\Delta I_{CC(AV)}$ differs with positive or negative input transitions, as shown in [Figure 11](#) and [Figure 12](#).

An example of a relaxation circuit using the 74HC132; 74HCT132 is shown in [Figure 13](#).



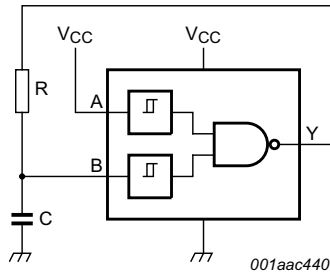
- (1) Positive-going edge.
- (2) Negative-going edge.

Fig 11. Average additional supply current as a function of V_{CC} for 74HC132; linear change of V_I between 0.1V_{CC} to 0.9V_{CC}.



- (1) Positive-going edge.
- (2) Negative-going edge.

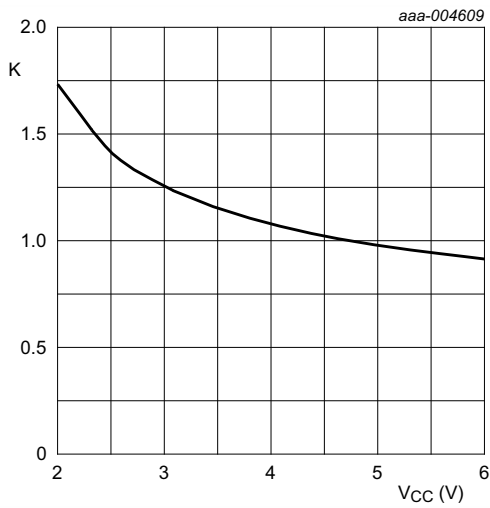
Fig 12. Average additional supply current as a function of V_{CC} for 74HCT132; linear change of V_I between 0.1V_{CC} to 0.9V_{CC}.



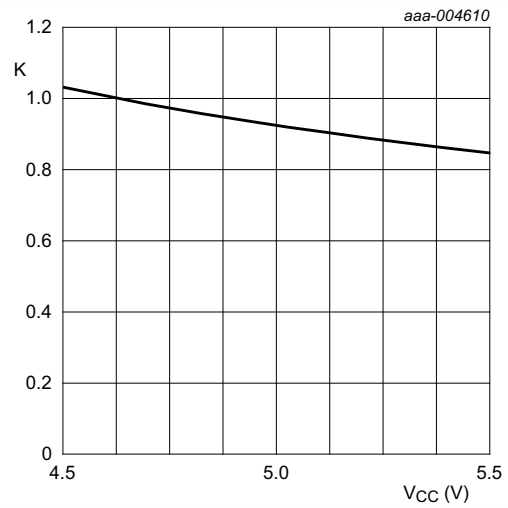
For 74HC132 and 74HCT132: $f = \frac{1}{T} \approx \frac{1}{K \times RC}$

For K-factor, see [Figure 14](#)

Fig 13. Relaxation oscillator



K-factor for 74HC132



K-factor for 74HCT132

Fig 14. Typical K-factor for relaxation oscillator

16. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

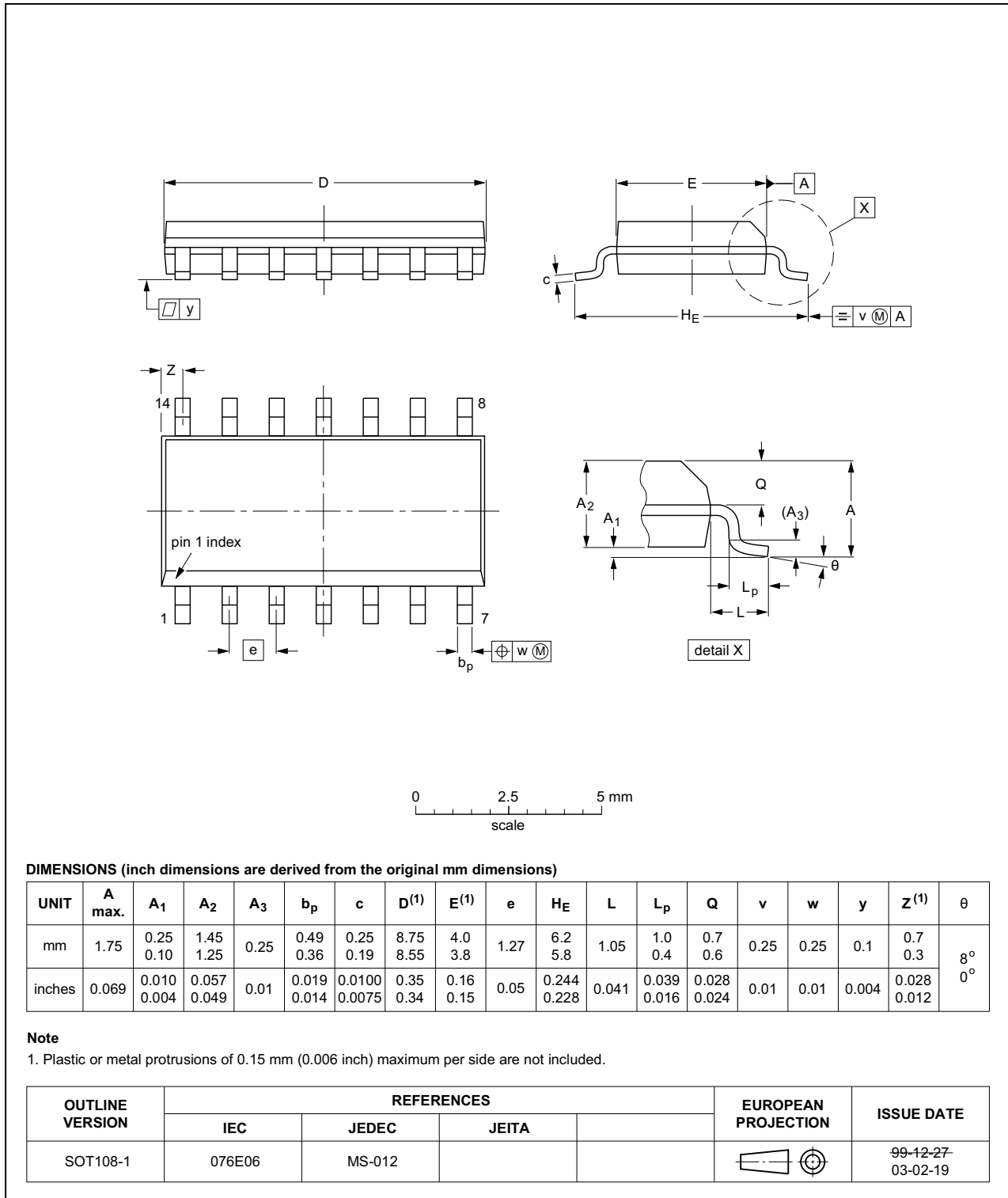


Fig 15. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

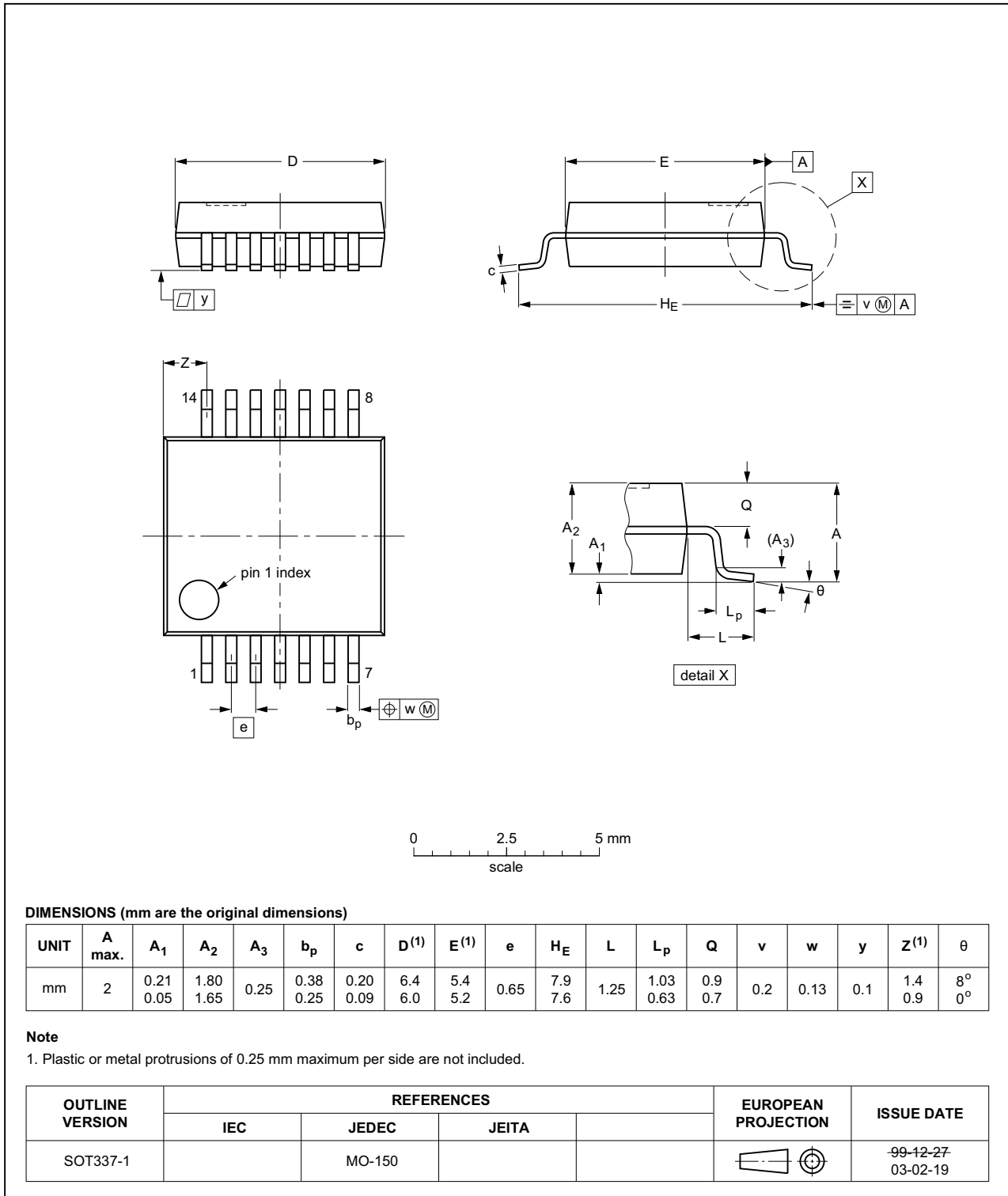


Fig 16. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

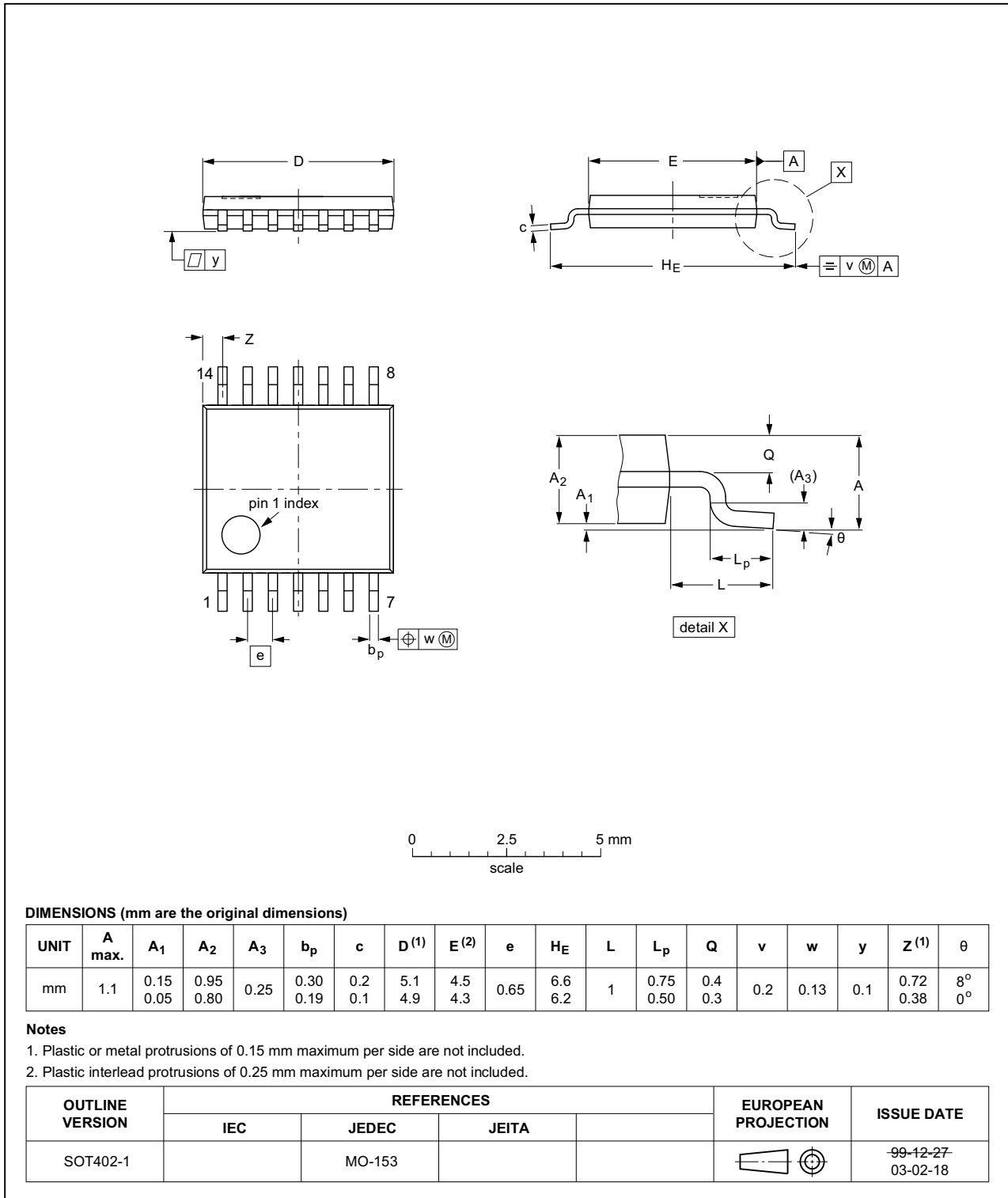


Fig 17. Package outline SOT402-1 (TSSOP14)

17. Abbreviations

Table 11. Abbreviations

| Acronym | Description |
|---------|---|
| CMOS | Complementary Metal-Oxide Semiconductor |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| MM | Machine Model |
| TTL | Transistor-Transistor Logic |

18. Revision history

Table 12. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|---------------------|--|-----------------------|---------------|---------------------|
| 74HC_HCT132 v.4 | 20151201 | Product data sheet | - | 74HC_HCT132 v.3 |
| Modifications: | <ul style="list-style-type: none"> Type numbers 74HC132N and 74HCT132N (SOT27-1) removed. | | | |
| 74HC_HCT132 v.3 | 20120830 | Product data sheet | - | 74HC_HCT132_CNV v.2 |
| Modifications: | <ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name where appropriate. Figure 14 added (typical K-factor for relaxation oscillator). | | | |
| 74HC_HCT132_CNV v.2 | 19970826 | Product specification | - | - |

19. Legal information

19.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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